

Title of Change:	Wafer fab transfer to onsemi Gresham, Oregon USA from onsemi Fab2, Oudenaarde, Belgium related to Fab2 sale		
Proposed Changed Material First Ship Date:	01 Sep 2022 or earlier if approved by customer		
Current Material Last Order Date:	31 Mar 2022 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	31 Aug 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office or Kevin.Mathews@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	01 Feb 2022		
PPAP Availability Date:	31 Mar 2022		
Additional Reliability Data:	Contact your local onsemi Sales Office or Catherine.DeKeukeleire@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.		
Change Category			
Category	Type of Change		
Design	Design Change in Routing		
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter		
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.		
Process - Assembly	Change of mold compound, Change of leadframe base material, Change of product marking		

Description and Purpose:

After the announcement on February 03rd, 2020 of the sale of Fab2, onsemi pursues the transfer of relevant products.

Before Last Order Date above: customers must provide Last-Time-Buy volume for products that will be transferred to manufacture the bridgebuild quantity in the current facility (fab2) before the selling.

After the last order date above: the orders will be placed on the new part number (replacement part) or on the receiving fab (products with the same part number).

Last Delivery Date above: subject to a commercial agreement, onsemi may extend the deliveries outside the 06 months windows which is the proposed date of implementation in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements but after depletion of inventory of the current material. However, such extended delivery conditions could be subject to an extension of the date code currently at 12 months



		Before Cha	nge Description	After Change Description		
Wafer Fab Site			enaarde, Belgium	onsemi, Gresham, Oregon, USA		
		50 mm	200 mm			
Equipment		150 mm Production Line		200 mm Production Line		
Mold Compound		G600		G700LS		
Leadframe		Cu		Cu Roughened		
Other Changes		Original Die		Additional 15k GDRV resistor to GND on chi		
			rom	То		
			: 887001 : 887100	Line 1: 887001G Line 1: 887100G		
			: 887103	Line 1: 887103G		
Product marking change		Line 1: 887104 Line 1: 887105		Line 1: 887104G Line 1: 887105G		
Product marking change			: 887105 : 887300	Line 1: 887105G Line 1: 887300G		
			: 887302	Line 1: 887302G		
			: 898031	Line 1: 898031G		
leason / Motivation for Change:	Source/Supply/Capacity Changes					
nticipated impact on fit, form, successfully passed the qual			d and validated based on the same Product Specification. The device has fication tests. Potential impacts can be identified, but due to testing fion to the PCN, associated risks are verified and excluded.			
ites Affected:						
onsemi Sites		External Foundry/Subcon Sites				
onsemi Carmona, Philippines		None				
nsemi Oudenaarde, Belgium						
nsemi, Gresham United States						
Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode					
Reliability Data Summary:						
NOTE: AEC-1pager is attached. To view attachments: 1. Download pdf copy of the PCN to you 2. Open the downloaded pdf copy of the 3. Click on the paper clip icon available o	PCN		/hottom portion of the	screen to reveal the Attachment field		

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Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle	
NCV898031D1R2G	NA	NCV887100D1R2G	
NCV887302D1R2G	NA	NCV887100D1R2G	
NCV887300D1R2G	NA	NCV887100D1R2G	
NCV887105D1R2G	NA	NCV887100D1R2G	
NCV887104D1R2G	NA	NCV887100D1R2G	
NCV887103D1R2G	NA	NCV887100D1R2G	
NCV887100D1R2G	NA	NCV887100D1R2G	
NCV887001D1R2G	NA	NCV887100D1R2G	

Appendix A: Changed Products

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV887300D1R2G		NCV887100D1R2G	NA	
NCV887103D1R2G		NCV887100D1R2G	NA	
NCV887100D1R2G		NCV887100D1R2G	NA	
NCV887001D1R2G		NCV887100D1R2G	NA	
NCV887104D1R2G		NCV887100D1R2G	NA	